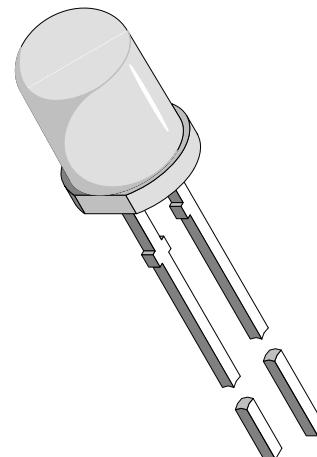


GaAs/GaAlAs IR Emitting Diodes in ø 5 mm (T-1^{3/4}) Package

Description

TSIP 52..-series are high efficiency infrared emitting diodes in GaAlAs on GaAs technology, molded in clear, bluegrey tinted plastic packages. In comparison with the standard GaAs on GaAs technology these emitters achieve about 70 % radiant power improvement at the same wavelength.

The forward voltages at low current and at high pulse current roughly correspond to the low values of the standard technology. Therefore these emitters are ideally suitable as high performance replacements of standard emitters. It is not necessary to modify the filter characteristics of the detector, the cover plates of transmitter and receiver or the supply voltage.



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Features

- Extra high radiant power and radiant intensity
- Low forward voltage
- Suitable for DC and high pulse current operation
- Standard T-1^{3/4} (ø 5 mm) package
- Angle of half intensity $\phi = \pm 17^\circ$
- Peak wavelength $\lambda_p = 950$ nm
- High reliability
- Good spectral matching to Si photodetectors

Applications

Infrared remote control units with high power requirements

Free air transmission systems

Infrared source for optical counters and card readers

IR source for smoke detectors

Absolute Maximum Ratings $T_{amb} = 25^\circ C$

Parameter	Test Conditions	Symbol	Value	Unit
Reverse Voltage		V_R	7	V
Forward Current		I_F	150	mA
Peak Forward Current	$t_p/T=0.5, t_p=100 \mu s$	I_{FM}	300	mA
Surge Forward Current	$t_p=100 \mu s$	I_{FSM}	3	A
Power Dissipation		P_V	210	mW
Junction Temperature		T_j	100	°C
Operating Temperature Range		T_{amb}	-55...+100	°C
Storage Temperature Range		T_{stg}	-55...+100	°C
Soldering Temperature	$t \leq 5\text{ sec}, 2 \text{ mm from case}$	T_{sd}	260	°C
Thermal Resistance Junction/Ambient		R_{thJA}	350	K/W

Basic Characteristics $T_{amb} = 25^\circ C$

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
Forward Voltage	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	V_F		1.3	1.8	V
Forward Voltage	$I_F = 1.5 \text{ A}, t_p = 100 \mu s$	V_F		2.4	3.2	V
Temp. Coefficient of V_F	$I_F = 100 \text{ mA}$	TK_{VF}		-1.3		mV/K
Reverse Current	$V_R = 5 \text{ V}$	I_R			100	μA
Junction Capacitance	$V_R = 0 \text{ V}, f = 1 \text{ MHz}, E = 0$	C_j		30		pF
Temp. Coefficient of ϕ_e	$I_F = 20 \text{ mA}$	$TK_{\phi e}$		-0.8		%/K
Angle of Half Intensity		ϕ		± 17		deg
Peak Wavelength	$I_F = 100 \text{ mA}$	λ_p		950		nm
Spectral Bandwidth	$I_F = 100 \text{ mA}$	$\Delta\lambda$		50		nm
Temp. Coefficient of λ_p	$I_F = 100 \text{ mA}$	$TK_{\lambda p}$		0.2		nm/K
Rise Time	$I_F = 100 \text{ mA}$	t_r		800		ns
Rise Time	$I_F = 1.5 \text{ A}$	t_r		500		ns
Fall Time	$I_F = 100 \text{ mA}$	t_f		800		ns
Fall Time	$I_F = 1.5 \text{ A}$	t_f		500		ns

Type Dedicated Characteristics $T_{amb} = 25^\circ C$

Parameter	Type	Test Conditions	Symbol	Min	Typ	Max	Unit
Radiant Intensity	TSIP5200	$I_F=100\text{mA}, t_p=20\text{ms}$	I_e	20	40		mW/sr
	TSIP5201	$I_F=100\text{mA}, t_p=20\text{ms}$	I_e	30	50		mW/sr
Radiant Intensity	TSIP5200	$I_F=1.5\text{A}, t_p=100\mu\text{s}$	I_e	240	520		mW/sr
	TSIP5201	$I_F=1.5\text{A}, t_p=100\mu\text{s}$	I_e	360	650		mW/sr
Radiant Power	TSIP5200	$I_F=100\text{mA}, t_p=20\text{ms}$	ϕ_e		22		mW
	TSIP5201	$I_F=100\text{mA}, t_p=20\text{ms}$	ϕ_e		25		mW

Typical Characteristics ($T_{amb} = 25^\circ C$ unless otherwise specified)

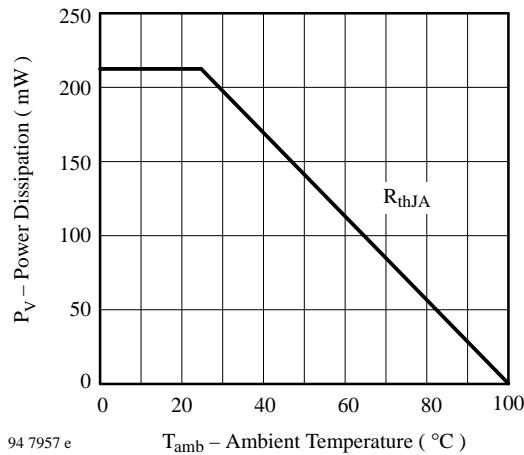


Figure 1 : Power Dissipation vs. Ambient Temperature

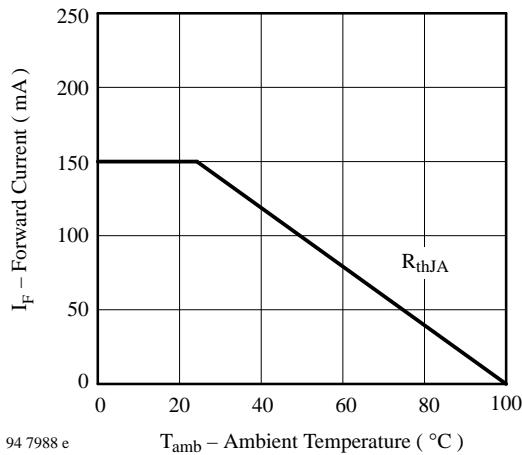


Figure 2 : Forward Current vs. Ambient Temperature

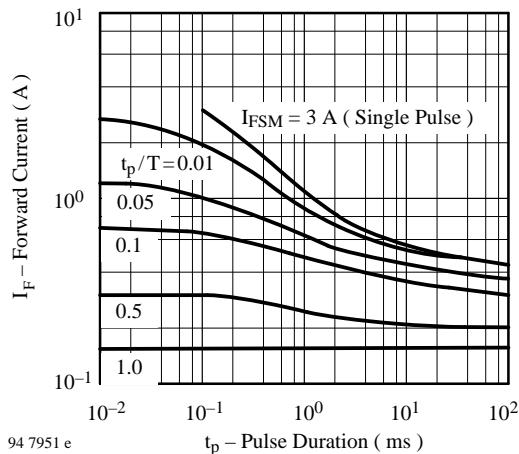


Figure 3 : Pulse Forward Current vs. Pulse Duration

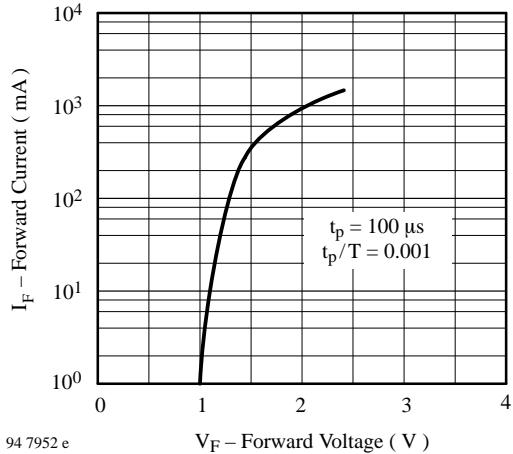


Figure 4 : Forward Current vs. Forward Voltage

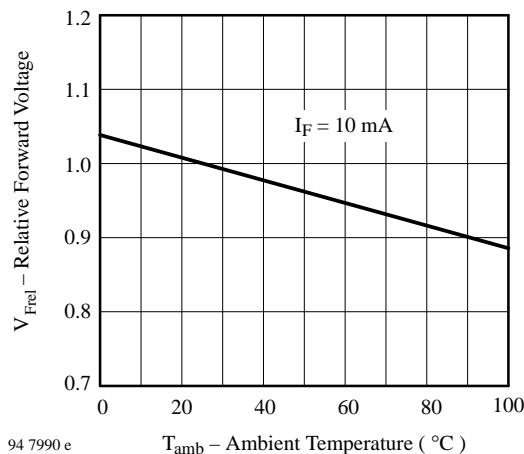


Figure 5 : Relative Forward Voltage vs. Ambient Temperature

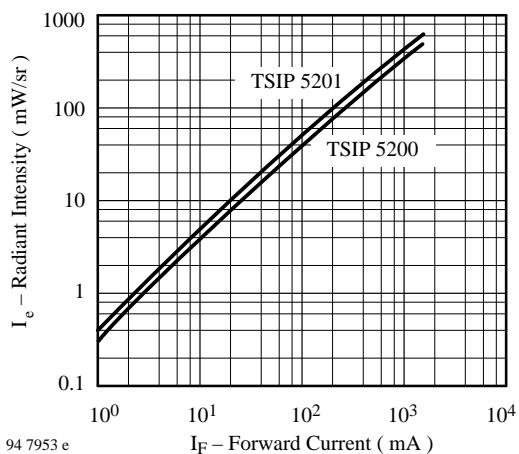


Figure 6 : Radiant Intensity vs. Forward Current

TSIP 520.

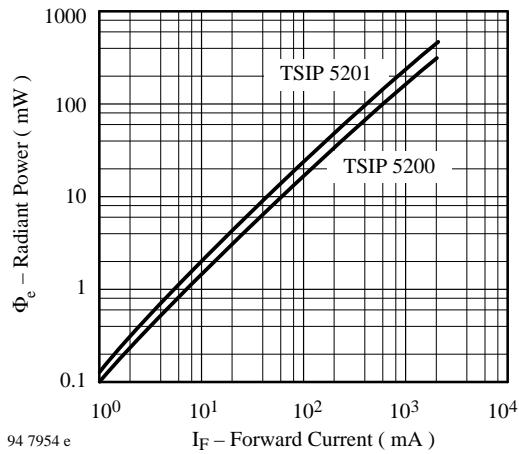


Figure 7 : Radian Power vs. Forward Current

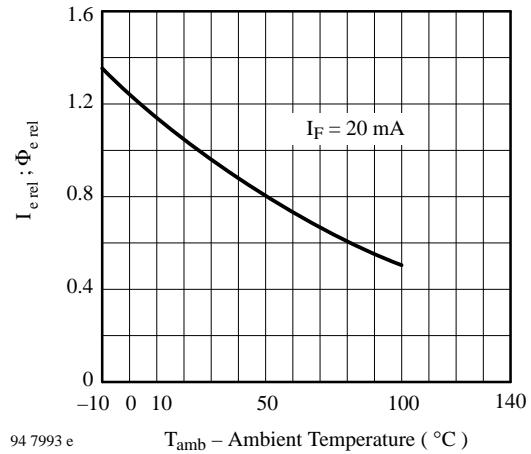


Figure 8 : Rel. Radian Intensity|Power vs. Ambient Temperature

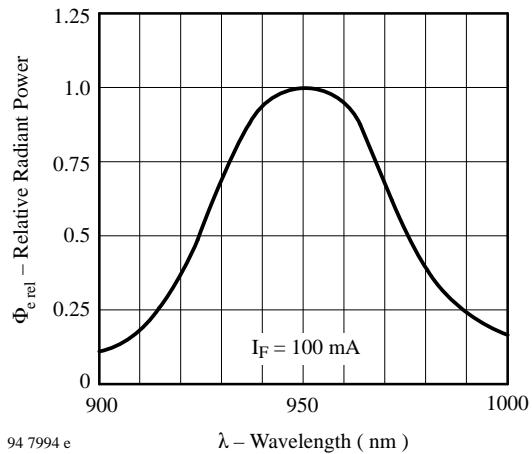


Figure 9 : Relative Radian Power vs. Wavelength

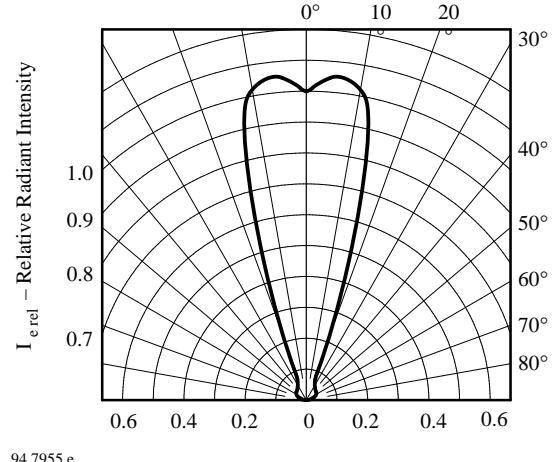
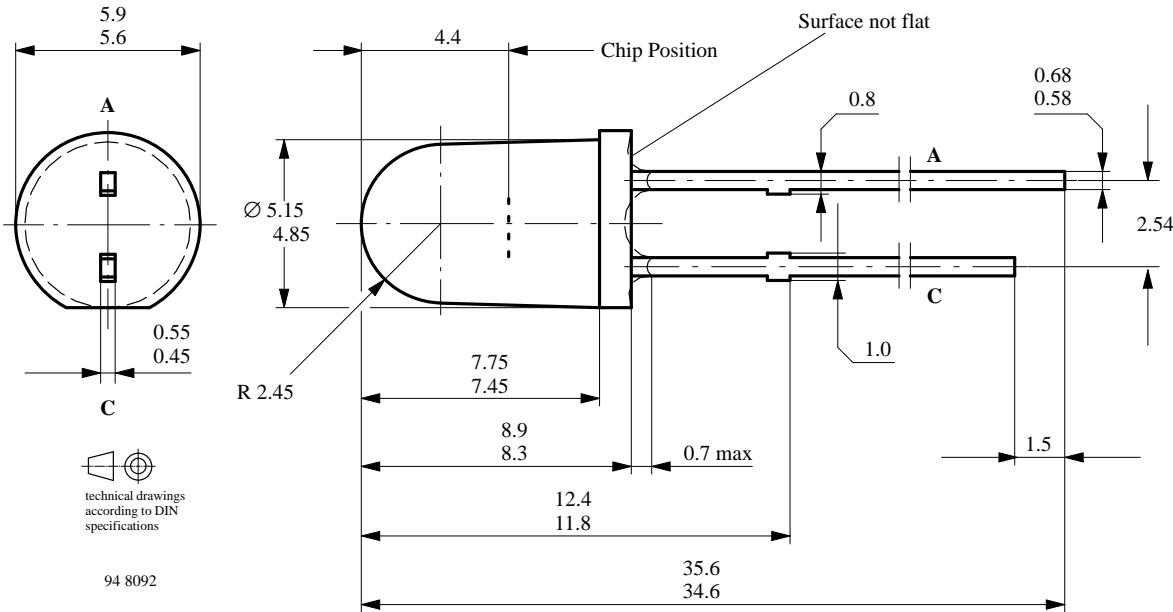


Figure 10 : Relative Radiant Intensity vs. Angular Displacement

Dimensions in mm



We reserve the right to make changes to improve technical design without further notice.

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